

1 **DECLARATION OF CONTINUATION-IN-PART FOR PATENT APPLICATION**

2 As a below named inventor, I hereby declare that:

3 My residence, post office address and citizenship are as stated
4 below next to my name.

5 I believe I am the original, first and joint inventor of the subject
6 matter which is claimed and for which a patent is sought on the
7 invention entitled: Semiconductor Processing Methods of Forming
8 Photoresist Over Silicon Nitride Materials, and Semiconductor Wafer
9 Assemblies Comprising Photoresist Over Silicon Nitride Materials,
10 identified as U.S. Patent Application Serial No. 09/457,093, filed on
11 December 7, 1999.

12 This application in part discloses and claims subject matter
13 disclosed in my earlier filed pending application, Semiconductor
14 Processing Methods of Forming Photoresist Over Silicon Nitride
15 Materials, and Semiconductor Wafer Assemblies Comprising Photoresist
16 Over Silicon Nitride Materials, Serial No. 09/057,155, filed April 7, 1998;

17 This application in part also discloses and claims subject matter
18 disclosed in my earlier filed pending application, Semiconductor
19 Processing Method of Promoting Photoresist Adhesion to an Outer
20 Substrate Layer Predominately Comprising Silicon Nitride, Serial No.
21 09/295,642, filed April 20, 1999;

EL 979950548

EL 844051467

1 I hereby state that I have reviewed and understand the contents
2 of the above identified specification, including the claims.

3 I hereby claim benefit under Title 35, United States Code, §120
4 in connection with said earlier filed applications;

5 I acknowledge the duty to disclose information known to me to be
6 material to patentability as defined in Title 37, Code of Federal
7 Regulations §1.56, including any such information which became available
8 between the filing dates of the prior applications and the national or
9 PCT international filing date of this application.

10 As to the subject matter of this application which is common to
11 said earlier applications, I do not know and do not believe that the
12 same was ever known or used in the United States of America before
13 our invention thereof or patented or described in any printed publication
14 in any country before our invention thereof, or more than one year prior
15 to said earlier applications, or in public use or on sale in the United
16 States of America more than one year prior to said earlier applications;

17 The common subject matter has not been patented or made the
18 subject of an inventor's certificate issued before the dates of said earlier
19 applications in any country foreign to the United States of America on
20 an application filed by me or my legal representatives or assigns more
21 than twelve months prior to said earlier applications; and
22

1 As to applications for patents or inventor's certificate on the
2 common subject matter filed in any country foreign to the United States
3 of America, prior to said earlier applications by me or my legal
4 representatives or assigns, I hereby claim foreign priority benefits under
5 Title 35, United States Code, §119 of any foreign application(s) for
6 patent or inventor's certificate listed below and have also identified below
7 any foreign application for patent or inventor's certificate having a filing
8 date before those of the applications on which priority is claimed:

9 PRIOR FOREIGN APPLICATION(S)

10 No such applications have been filed.
11

12 As to the subject matter of this application which is not common
13 to said earlier applications, I do not know and do not believe that the
14 same was ever known or used in the United States of America before
15 our invention thereof or patented or described in any printed publication
16 in any country before our invention thereof, or more than one year prior
17 to this application, or in public use or on sale in the United States of
18 America more than one year prior to this application;

19 Said non-common subject matter has not been patented or made
20 the subject of an inventor's certificate issued before the date of this
21 application in any country foreign to the United States of America on
22

1 an application filed by me or my legal representatives or assigns more
2 than twelve months prior to this application; and

3 As to applications for patents or inventor's certificate on the
4 invention filed in any country foreign to the United States of America
5 prior to this application by me or my legal representatives or assigns, I
6 hereby claim foreign priority benefits under Title 35, United States Code,
7 §119 of any foreign application(s) for patent or inventor's certificate
8 listed below and certificate having a filing date before those of the
9 applications on which priority is claimed:

10 PRIOR FOREIGN APPLICATION(S)

11 No such applications have been filed.
12

13 I hereby declare that all statements made herein of my own
14 knowledge are true and that all statements made on information and
15 belief are believed to be true; and further that these statements were
16 made with the knowledge that willful false statements and the like so
17 made are punishable by fine or imprisonment, or both, under
18 Section 1001 of Title 18 of the United States Code and that such willful
19 false statement may jeopardize the validity of the application or any
20 patent issued therefrom.
21
22

* * * * *

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Inventor's Signature: John T. Moore

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* * * * *

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* * * * *

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* * * * *

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